PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHAN BAE KIM	07/25/2007
JONG MIN LEE	07/25/2007
CHAE O CHUNG	07/25/2007
HYEON JU AN	07/25/2007
HYO SEOK LEE	07/25/2007
SUNG KYU MIN	07/25/2007

RECEIVING PARTY DATA

Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyoungki-do
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11834264

CH $40.00 11834264

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	CU-5857 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park

Total Attachments: 2
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UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:
Name : Chan Bae KIM
Address : 107-303, Hyundai Apt., Ami 1-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea
Name : Jong Min LEE
Address : 717-1004, Dongah Apts., Yeongtong-dong, Paldal-gu, Suwon-si, Gyeonggi-do, Korea
Name : Chae O CHUNG
Address : 104-504, Hyundai I-Park Apts., Sadong-ri, Daewol-myeon, Icheon-si, Gyeonggi-do, Korea
Name : Hyeon Ju AN
Address : 105-704, Hwanggol Jugong Apts. 2, Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea
Name : Hyo Seok LEE
Address : 105-702, Chonggu Apts., Hansolmaeul, Jeongja 2-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea
Name : Sung Kyu MIN
Address : 128-461, Haengdang-dong, Seongdong-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:
Name : Hynix Semiconductor Inc.
Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE UTILIZING LOW DIELECTRIC LAYER FILLING GAPS BETWEEN METAL LINES

(TITLE)

and which is found in *(check one applicable item below)*

☒ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. ______________ filed on ______________

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

July 25, 2007
Date

Kim Chan Bae
INVENTOR: Chan Bae KIM

July 25, 2007
Date

LEE JONG MIN
INVENTOR: Jong Min LEE

July 25, 2007
Date

Chung Chai O
INVENTOR: Chae O CHUNG

July 25, 2007
Date

~~Lee H~~ An Hyeon Ju
INVENTOR: Hyeon Ju AN

July 25, 2007
Date

Lee Hyo Seok
INVENTOR: Hyo Seok LEE

July 25, 2007
Date

Min Sung Kyu
INVENTOR: Sung Kyu MIN